

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims 8-11 without prejudice:

1. (ORIGINAL) A thin-film capacitor device comprising:
 - a lower electrode formed on a surface of a core substrate;
 - a dielectric film generated from a metal film formed on said lower electrode;
 - an upper electrode formed on said dielectric film; and
 - a first conductor extending from said lower electrode toward an opposite surface of said core substrate, wherein
 - a first electrode pad is provided on said first conductor and a second electrode pad is provided on a second conductor connected to said upper electrode.
2. (ORIGINAL) A thin-film capacitor device as claimed in claim 1, wherein
 - said first conductor is filled into a groove formed in said core substrate when forming said lower electrode thereon, and
 - said opposite surface of said core substrate is formed by grinding said core substrate until said groove is exposed.
3. (ORIGINAL) A thin-film capacitor device as claimed in claim 2, wherein said metal film is made of tantalum or titanium, and
 - said dielectric film is generated by anodic oxidation of said tantalum or titanium.
4. (ORIGINAL) A thin-film capacitor device as claimed in claim 2, wherein
 - by selective anodic oxidation, said metal film is divided into a dielectric film region and a first and a second metal film region,
 - said first conductor connected to said lower electrode is connected to a lower surface of said first metal film region,
 - a third conductor is connected to an upper surface of said first metal film region,

said second conductor connected to said upper electrode is connected to an upper surface of said second metal film region, and

a fourth conductor is connected to a lower surface of said second metal film region, and wherein

first to fourth electrode pads are provided on said first to fourth conductors, respectively, and a capacitor is formed by said dielectric film region, said upper electrode, and said lower electrode.

5. (ORIGINAL) A thin-film capacitor device as claimed in claim 4, wherein said metal film is made of tantalum or titanium, and

said dielectric film is generated by anodic oxidation of said tantalum or titanium.

6. (ORIGINAL) A thin-film capacitor device mounting module containing a thin-film capacitor device and a multilayer wiring circuit having external connection terminals, wherein

said thin-film capacitor device comprises:

a dielectric film region and a first and a second metal film region into which a metal film formed on a core substrate is divided by selective anodic oxidation;

a first conductor connected to a lower electrode at a lower surface of said first metal film region;

a third conductor connected to an upper surface of said first metal film region;

a second conductor connected to an upper electrode at an upper surface of said second metal film region; and

a fourth conductor connected to a lower surface of said second metal film region, and wherein:

first to fourth electrode pads are provided on said first to fourth conductors, respectively, and a capacitor is formed by said dielectric film region, said upper electrode, and said lower electrode, and

said first electrode pad and said fourth electrode pad provided on said thin-film capacitor device are connected to said multilayer wiring circuit, and a semiconductor device is connected to said second electrode pad and said third electrode pad provided on said thin-film capacitor device.

7. (ORIGINAL) A thin-film capacitor device mounting module as claimed in claim 6, wherein

said module contains a plurality of said thin-film capacitor devices, and
said first electrode pad and said fourth electrode pad provided on each of
said thin-film capacitor devices are connected to said multilayer wiring circuit.

8. (CANCELLED)

9. (CANCELLED)

10. (CANCELLED)

11. (CANCELLED)